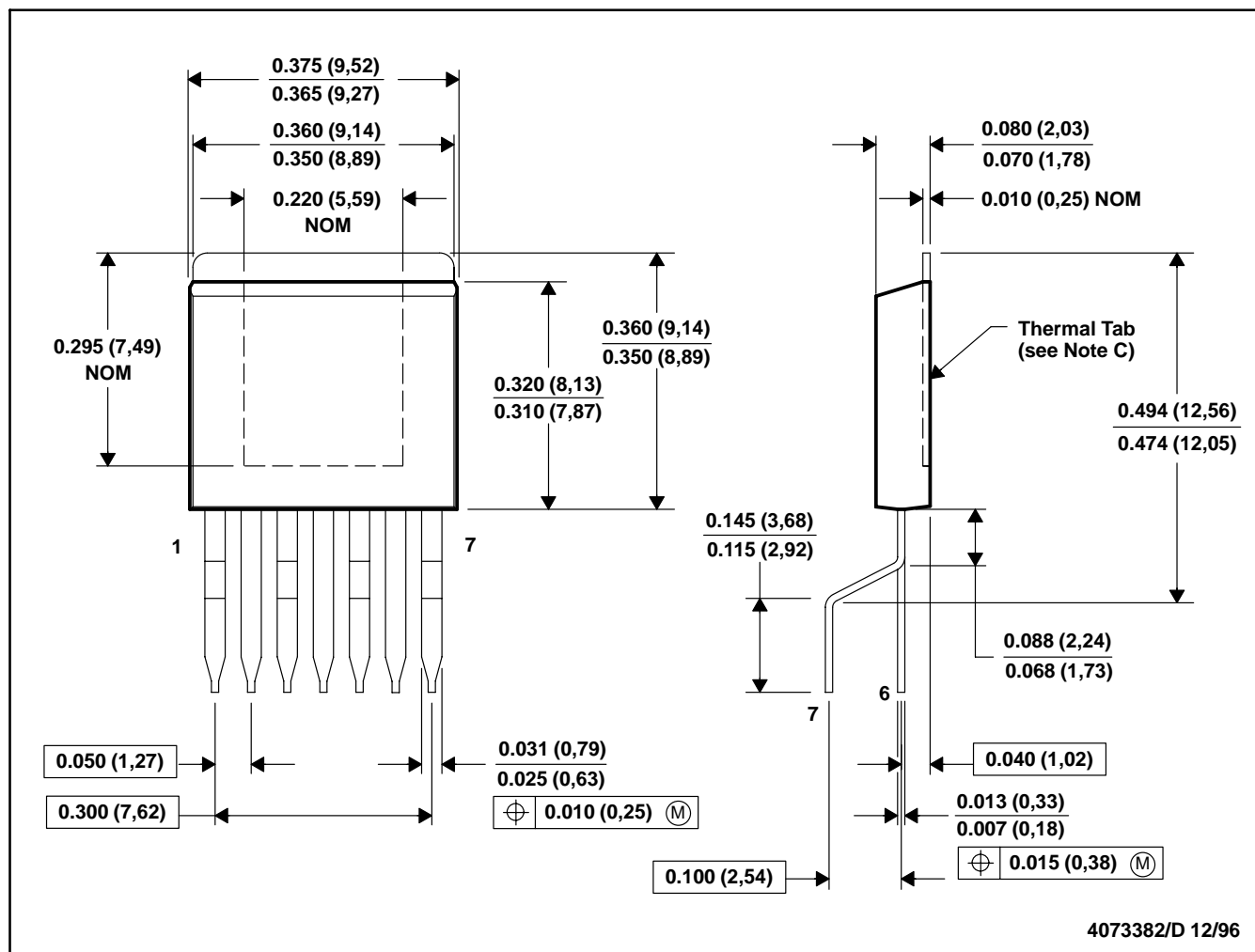


## KTM (R-PSFM-T7)

## PowerFLEX™ PLASTIC FLANGE-MOUNT PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. The center lead is in electrical contact with the thermal tab.  
 D. Dimensions do not include mold protrusions, not to exceed 0.006 (0,15).

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